

500mW Hermetically Sealed Glass Fast Switching Diodes

FEATURES

- Small hermetically sealed glass SMD package

- High switching speed: Max. 4 ns
- Continuous reverse voltage: Max. 75V
- Repetitive peak reverse voltage: Max. 75V
- Repetitive peak forward current: Max. 450 mA





SOD80C

RŏHS

MECHANICAL DATA

- Polarity: Indicated by black cathode band

Hermetically Sealed Glass

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)				
PARAMETER		SYMBOL	VALUE	UNIT
Repetitive Peak Reverse Voltage		V_{RRM}	75	V
Continuous Reverse Voltage		V_R	75	V
Continuous Forward Current Fig. 2, (Note 1)		I _F	200	mA
Repetitive Peak Forward Current		I _{FRM}	450	mA
Non-Repetitive Peak Forward Surge Curr	ent			
Square Wave : T _J =25°C Prior to Surge : S	See Fig. 4			
t=1µs		FSM	4	А
t=1ms		D '	1	
t=1s			0.5	
Total Power Dissipation	T _{amb} =25°C, (Note 1)	P _{tot}	500	mW
Operating Junction Temperature	1	TJ	200	°C
Storage Temperature Range		T _{STG}	-65 to 200	°C

PA	SYMBOL	MIN	MAX	UNIT	
Forward Voltage	See Fig. 3 I _F =10mA	V _F	-	1.0	V
Reverse Leakage Current	V _R =20V See Fig. 5	_	-	25.0	nA
	$V_R=20V$ $T_j=150$ °C	I _R	-	50.0	μA
Junction Capacitance	$V_R=0$ f=1.0MHz	CJ	-	4.0	pF
Reverse Recovery Time	(Note 2)	t _{rr}	-	4.0	ns
Forward Recovery Voltage	I _F =50 mA tr=20ns	$V_{\rm fr}$	-	2.5	V

Note 1 : Device mounted on an FR4 printed-circuit board

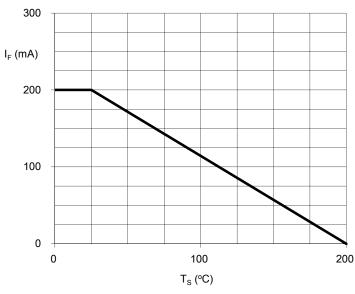
Note 2 : Reverse recovery test conditions : I_F =10mA, I_R =60mA, R_L =100 Ω , I_{RR} =1m A



RATINGS AND CHARACTERISTICS CURVES

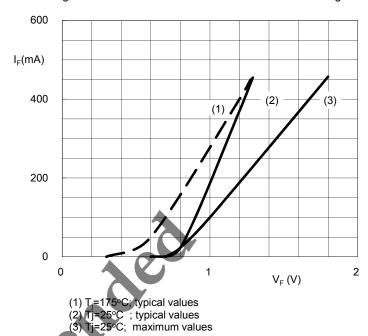
 $(T_A=25^{\circ}C \text{ unless otherwise noted})$

Fig. 1 Maximum Permissible Continuous Forward Current As A Function of Ambient Temperature

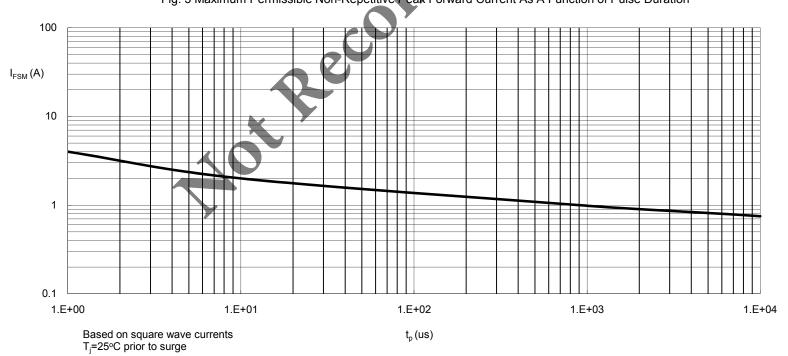


Device mounted on an FR4 printed-circuit

Fig. 2 Forward Current As A Function of Forward Voltage



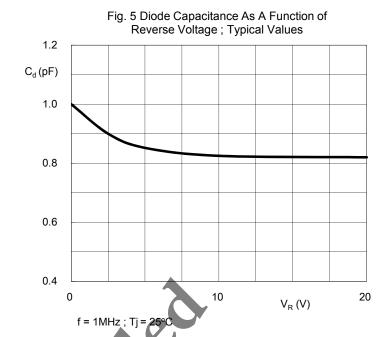






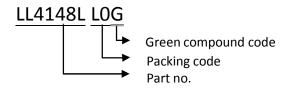
Junction Temperature 1000 I_R (uA) 100 (1) (2) (3) 10 f = 1MHz : Tj = 28c0 0.1 0.01 (1) V_R =75V ; maximum values (2) V_R =75V ; typical values (3) V_R =20V ; typical values

Fig. 4 Reverse Current As A Function of

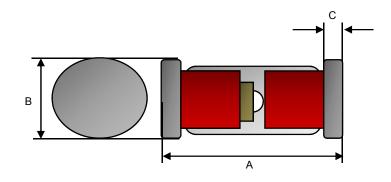




ORDER INFORMATION (EXAMPLE)

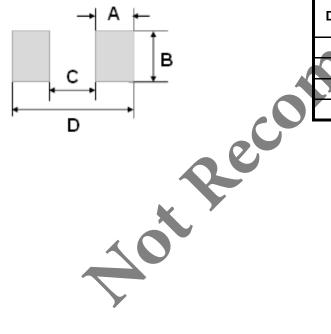


PACKAGE OUTLINE DIMENSION



DIM.	Unit (mm)		Unit (inch)		
Dilvi.	Min	Max	Min	Max	
Α	3.30	3.70	0.130	0.146	
В	1.40	1.60	0.055	0.063	
С	0.20	0.50	0.008	0.020	

SUGGEST PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)	
DIIVI.	Тур.	Тур.	
A	1.25	0.049	
В	2.00	0.079	
O	2.50	0.098	
J	5.00	0 197	



Aot Reconnine nated

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or seling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.

Document Number: DS_S1501007 Version: C15